

**IN THE UNITED STATES DISTRICT COURT  
FOR THE DISTRICT OF DELAWARE**

ELM 3DS INNOVATIONS, LLC,	:	
	:	
Plaintiff,	:	
	:	
v.	:	C.A. No. 14-cv-1430-LPS
	:	
SAMSUNG ELECTRONICS CO., LTD., et	:	<b>JURY TRIAL DEMANDED</b>
al.,	:	
	:	
Defendants.	:	
	:	
ELM 3DS INNOVATIONS, LLC,	:	
	:	
Plaintiff,	:	
	:	
v.	:	C.A. No. 14-cv-1431-LPS
	:	
MICRON TECHNOLOGY, INC., et al.,	:	<b>JURY TRIAL DEMANDED</b>
	:	
Defendants.	:	
	:	
ELM 3DS INNOVATIONS, LLC,	:	
	:	
Plaintiff,	:	
	:	
v.	:	C.A. No. 14-cv-1432-LPS
	:	
SK HYNIX INC., et al.,	:	<b>JURY TRIAL DEMANDED</b>
	:	
Defendants.	:	
	:	

**PLAINTIFF’S EXHIBITS TO PLAINTIFF’S CLAIM CONSTRUCTION BRIEFS**

<b>Exhibit</b>	<b>Description</b>
A	Declaration of Shefford Baker dated January 25, 2019
B	Al-sarawi, Said F., <i>A Review of 3-D Packaging Technology</i> , IEEE Transactions on Components, Packaging, and Manufacturing Technology, Part B, Vol. 21, No. 1 (February 1998) (ELMEX_00000001)

C	<i>Merriam Webster's Collegiate Dictionary</i> (10th ed. 1999) (ELMEX_00000227)
D	Email from Citroen to Ford dated January 24, 2019 re Elm v. Defendants: Indefiniteness Position
E	Defendants' Fourth Amended Invalidity Contentions (excerpts) dated January 28, 2019
F	Müller, Jochen, et al, <i>Smart Card Assembly Requires Advanced Pre-Assembly Methods</i> , Semiconductor International (July 2000) (ELM3DS00030869)
G	Francis, David, <i>Thinning Wafers For Flip Chip Applications, High Density Interconnect</i> (ELM3DS00036832)
H	McGrath, Dylan, <i>Thinning Wafers Beyond CMP</i> , Electronic News, July 6, 1998 (ELMEX_00000175)
I	Gurnett, Keith and Tom Adams, <i>Ultra-thin semiconductor wafer applications and processes</i> , The Advanced Semiconductor Magazine, Vol. 19 No. 4 (May 2006) (ELMEX_00000096)
J	Appellants' Opening Brief, <i>Samsung Electronics Co., Ltd. et al v. Elm 3DS Innovations LLC</i> , Nos. 2017-2474 et al (Fed. Cir. Feb. 16, 2018)
K	Appellants' Reply Brief, <i>Samsung Electronics Co., Ltd. et al v. Elm 3DS Innovations LLC</i> , Nos. 2017-2474 et al (Fed. Cir. June 5, 2018)
L	Prosecution History of U.S. Pat. App. No. 12/268,386, September 30, 2015 Supplemental Response and Amendment

Dated: December 12, 2019

Respectfully submitted,

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